Product End-of-Life Disassembly Instructions

Product Category: Data Storage Devices
Marketing Name / Model **[List multiple models if applicable.]**
Ultrium 2, LTO 448m (array module) / DW019A

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx screwdrivers	T-5, T-8 & T-10
Crosshead screwdriver / knife	NA
Scissors	NA

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

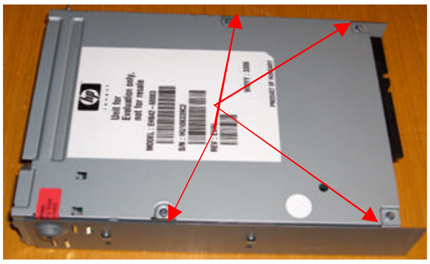
3.1.1. Remove the mechanism from the array cradle. Secured with 4 x T-10 screws, 2 x on either side. Remove the SCSI I/O PCA (> 10 square cm's) from the cradle using a T-10.
3.1.2. Clip off front panel
3.1.3. Remove lid by removing 4 x T-8 screws. See image 2.
3.1.4. Remove main PCA. Disconnect 3 x FPCs and lift out the PCA - > 10 square cm's. See image 3.
3.1.5. Remove the reel motor PCA - > 10 square cm's. Remove take up reel – use a pair of scissors to cut the tape; remove grab stop; move carrier approximately 2 cm into the mechanism and slide out the reel motor PCA. See images 4-7.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1)

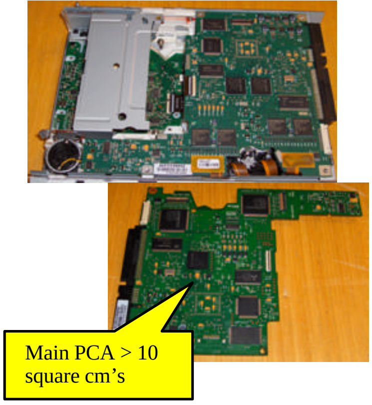
Ultrium 1, 2 & 3 half height tape drive

2)



Remove 4 x T-8 screws to remove the lid.

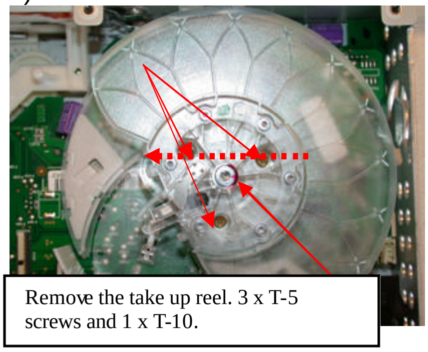
3)



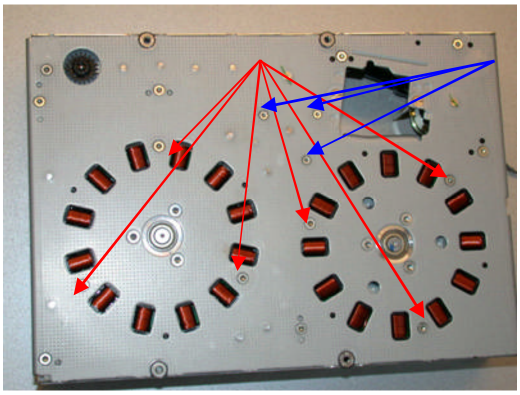
Main PCA > 10 square cm's

Main PCA > 10 square cm's

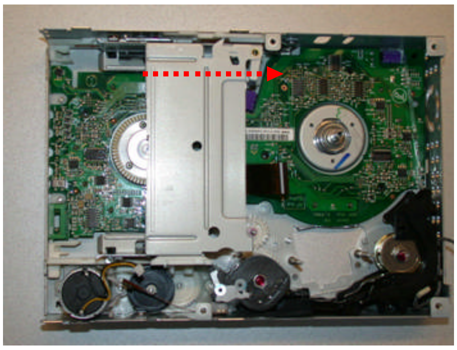
4)



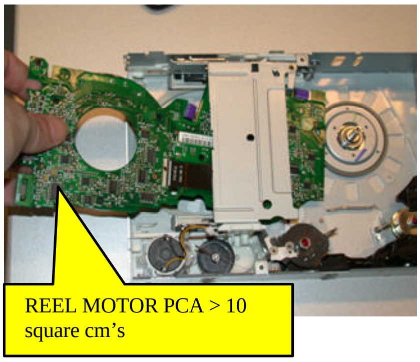
Remove the take up reel. 3 x T-5 screws and 1 x T-10.



5)
Remove 6 x T-8 and 3 x T-5 screws from rear of mech.



6)
Move carrier approximately 2 cm into the mechanism – directon of arrow.



7)
Reel motor PCA > 10 square cm's